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IGBT

April 2001

SGS5N60RUFD

Short Circuit Rated IGBT

General Description

Fairchild's RUFD series of Insulated Gate Bipolar Transistors (IGBTs) provide low conduction and switching losses as well as short circuit ruggedness. The RUFD series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

Features

- Short circuit rated 10us @ $T_C = 100$ °C, $V_{GE} = 15$ V
- · High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.2 \text{ V} @ I_C = 5A$
- · High input impedance
- CO-PAK, IGBT with FRD : $t_{rr} = 37$ ns (typ.)

Application

AC & DC Motor controls, general purpose inverters, robotics, servo controls





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		SGS5N60RUFD	Units
V _{CES}	Collector-Emitter Voltage		600	V
V _{GES}	Gate-Emitter Voltage		± 20	V
_	Collector Current	@ $T_C = 25^{\circ}C$	8	Α
I _C	Collector Current	@ T _C = 100°C	5	Α
I _{CM (1)}	Pulsed Collector Current		15	Α
T _{SC}	Short Circuit Withstand Time	@ T _C = 100°C	10	μs
I _F	Diode Continuous Forward Current	@ T _C = 100°C	8	Α
I _{FM}	Diode Maximum Forward Current		56	Α
P_{D}	Maximum Power Dissipation	@ $T_C = 25^{\circ}C$	35	W
	Maximum Power Dissipation	@ T _C = 100°C	14	W
T _J	Operating Junction Temperature		-55 to +150	°C
T _J T _{stg}	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering purposes, 1/8" from case for 5 seconds		300	°C

Notes

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		3.5	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		5.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chai	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 250uA	600			V
$\Delta B_{VCES}/$ ΔT_{J}	Temperature Coeff. of Breakdown Voltage	$V_{GE} = 0V$, $I_C = 1mA$		0.6		V/°C
I _{CES}	Collector Cut-off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	μΑ
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	racteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 5mA$, $V_{CE} = V_{GE}$	5.0	6.0	8.5	V
•	Collector to Emitter	$I_C = 5A$, $V_{GE} = 15V$		2.2	2.8	V
V _{CE(sat)}	Saturation Voltage	$I_{C} = 8A$, $V_{GE} = 15V$		2.5		V
D		, , , , , ,	Ш	1		I
Oynamic C _{ies}	C Characteristics Input Capacitance			354		pF
C _{oes}	Output Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$		67		pF
C _{res}	Reverse Transfer Capacitance	f = 1MHz		14		pF
	ng Characteristics Turn-On Delay Time			13		ns
t _{d(on)}	Turn-On Delay Time			13		ns
t _r	Rise Time			24		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 5\text{A},$		34	50	nS
t _f	Fall Time	$R_{G} = 40\Omega, V_{GE} = 15V,$		136	200	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		88		μJ
E _{off}	Turn-Off Switching Loss			107		μJ
E _{ts}	Total Switching Loss			195	280	μJ
t _{d(on)}	Turn-On Delay Time			13		ns
t _r	Rise Time			26		ns
$t_{d(off)}$	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 5\text{A},$		40	60	ns
t _f	Fall Time	$R_G = 40\Omega, V_{GE} = 15V,$		250	350	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C		103		μJ
E _{off}	Turn-Off Switching Loss			220		μJ
E _{ts}	Total Switching Loss			323		μJ
T _{sc}	Short Circuit Withstand Time	V _{CC} = 300 V, V _{GE} = 15V @ T _C = 100°C	10			μs
Qg	Total Gate Charge			16	24	nC
Q _{qe}	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, I_{C} = 5\text{A},$		3	6	nC
Q _{gc}	Gate-Collector Charge	V _{GE} = 15V		7	14	nC
						i e

Electrical Characteristics of DIODE T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
V	Diode Forward Voltage	I Q A	$T_C = 25^{\circ}C$		1.4	1.7	V
V_{FM}	Diode Forward Voltage	I _F = 8A	T _C = 100°C		1.3] v
	t _{rr} Diode Reverse Recovery Time	ode Reverse Recovery Time	$T_C = 25^{\circ}C$		37	55	no
^l rr			T _C = 100°C		55		ns
1	Diode Peak Reverse Recovery	I _F = 8A,	$T_C = 25^{\circ}C$		3.5	5.0	Α
Irr	Current	di/dt = 200 A/μs	T _C = 100°C		4.5		A
Q _{rr}	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		65	138	nC
			T _C = 100°C		124		110

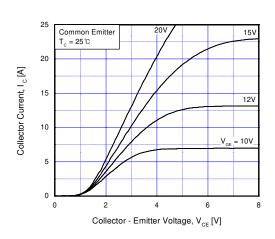
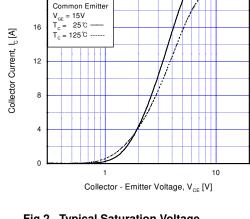


Fig 1. Typical Output Chacracteristics



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Fig 2. Typical Saturation Voltage Characteristics

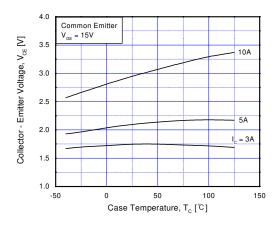


Fig 3. Saturation Voltage vs. Case
Temperature at Variant Current Level

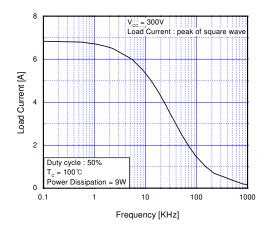


Fig 4. Load Current vs. Frequency

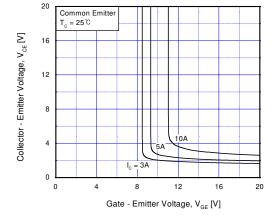


Fig 5. Saturation Voltage vs. V_{GE}

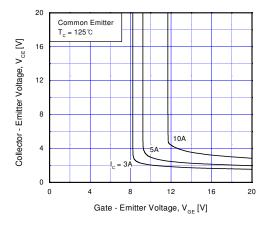
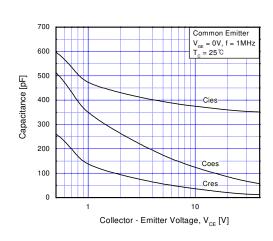


Fig 6. Saturation Voltage vs. V_{GE}

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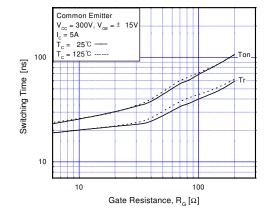
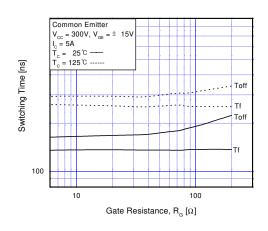


Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



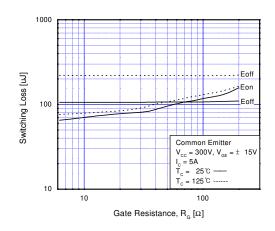
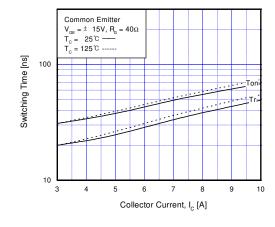


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



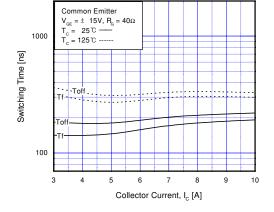
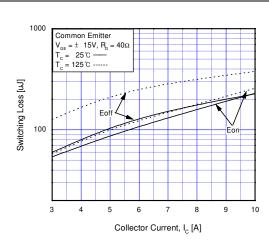


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



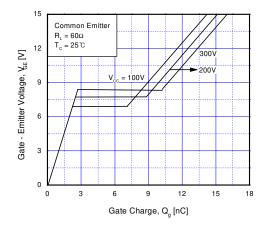
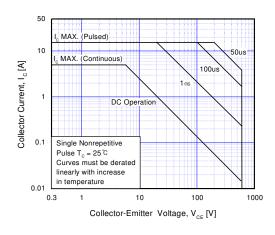


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



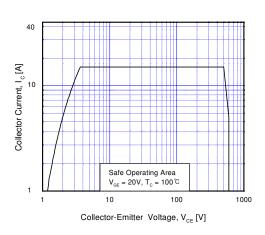


Fig 15. SOA Characteristic

Fig 16. Turn-Off SOA Characteristics

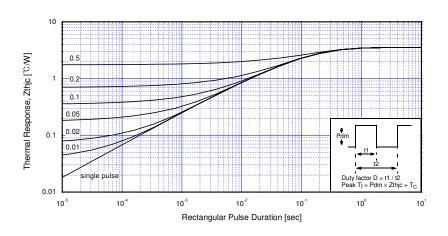
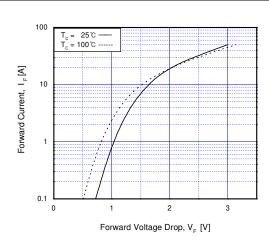


Fig 17. Transient Thermal Impedance of IGBT

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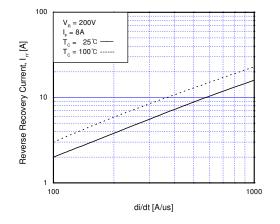
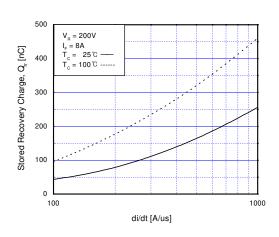


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



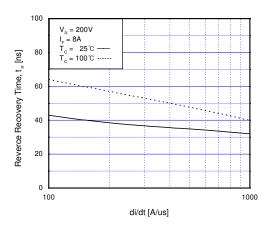
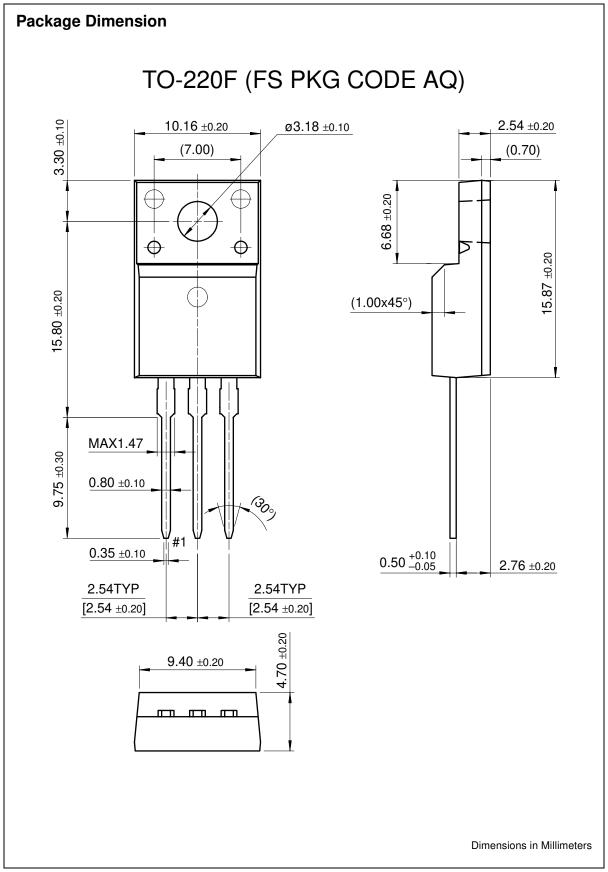


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



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